


PCN Number:	20230730004.1	PCN Date:	August 14, 2023																																										
Title:	Datasheet for BQ25672																																												
Customer Contact:	Change Management	Dept:	Quality Services																																										
Proposed 1st Ship Date:	Nov. 14, 2023																																												
Change Type:																																													
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site																																											
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material																																											
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process																																											
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site																																											
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials																																											
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Notification Details																																													
Description of Change:																																													
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below.</p>																																													
<div style="display: flex; justify-content: space-between; align-items: center;"> <div style="display: flex; align-items: center;">  <div> TEXAS INSTRUMENTS </div> </div> <div style="text-align: right;"> BQ25672 <small>SLUSEB9B – DECEMBER 2020 – REVISED JULY 2023</small> </div> </div>																																													
<table border="0" style="width: 100%;"> <thead> <tr> <th style="text-align: left;">Changes from Revision A (May 2021) to Revision B (July 2023)</th> <th style="text-align: right;">Page</th> </tr> </thead> <tbody> <tr><td>• Corrected common drain to common source in ACDRVx pin function in Section 6</td> <td style="text-align: right;">4</td> </tr> <tr><td>• Clarified /QON pull up voltage in Section 6</td> <td style="text-align: right;">4</td> </tr> <tr><td>• Deleted SDRV connected to BAT when shipFET disabled as an option in Section 6</td> <td style="text-align: right;">4</td> </tr> <tr><td>• Updated: V_{SYSMIN_REG_ACC}</td> <td style="text-align: right;">8</td> </tr> <tr><td>• Updated V_{OTG_ACC}</td> <td style="text-align: right;">8</td> </tr> <tr><td>• Changed Functional Block Diagram.....</td> <td style="text-align: right;">23</td> </tr> <tr><td>• Corrected default charge current to 1 A in Section 8.3.2</td> <td style="text-align: right;">24</td> </tr> <tr><td>• Clarified PFM peak inductor current in Section 8.3.6.4</td> <td style="text-align: right;">33</td> </tr> <tr><td>• Added charge current clamp during SYSMIN operation in Section 8.3.9.2</td> <td style="text-align: right;">38</td> </tr> <tr><td>• Clarified trickle to precharge regulation in Section 8.3.9.2</td> <td style="text-align: right;">38</td> </tr> <tr><td>• Added SDRV typical output voltage and current to Section 8.3.12</td> <td style="text-align: right;">45</td> </tr> <tr><td>• Updated I2C terminology in text and figures in Section 8.3.14</td> <td style="text-align: right;">48</td> </tr> <tr><td>• Corrected REG0x03 default charge current to 1A and max charge current to 3 A in Section 8.5.1</td> <td style="text-align: right;">53</td> </tr> <tr><td>• Changed REG0x09 bit5 from RESERVED to STOP_WD_CHG in Section 8.5.1</td> <td style="text-align: right;">53</td> </tr> <tr><td>• Added REG0x10 bits5-4 in Section 8.5.1</td> <td style="text-align: right;">53</td> </tr> <tr><td>• Clarified REG0x14 and REG0x33 regarding reporting IBAT discharge current in Section 8.5.1</td> <td style="text-align: right;">53</td> </tr> <tr><td>• Changed REG0x2E to no longer recommend 12-bit ADC setting in Section 8.5.1</td> <td style="text-align: right;">53</td> </tr> <tr><td>• Changed REG0x2E to Running average (not available for IBAT discharge) in Section 8.5.1</td> <td style="text-align: right;">53</td> </tr> <tr><td>• Corrected PN and DEV_REV naming in REG0x48 in Section 8.5.1</td> <td style="text-align: right;">53</td> </tr> <tr><td>• Added optional input snubber/TVS to application diagrams in Section 9.2</td> <td style="text-align: right;">126</td> </tr> </tbody> </table>				Changes from Revision A (May 2021) to Revision B (July 2023)	Page	• Corrected common drain to common source in ACDRVx pin function in Section 6	4	• Clarified /QON pull up voltage in Section 6	4	• Deleted SDRV connected to BAT when shipFET disabled as an option in Section 6	4	• Updated: V _{SYSMIN_REG_ACC}	8	• Updated V _{OTG_ACC}	8	• Changed Functional Block Diagram.....	23	• Corrected default charge current to 1 A in Section 8.3.2	24	• Clarified PFM peak inductor current in Section 8.3.6.4	33	• Added charge current clamp during SYSMIN operation in Section 8.3.9.2	38	• Clarified trickle to precharge regulation in Section 8.3.9.2	38	• Added SDRV typical output voltage and current to Section 8.3.12	45	• Updated I2C terminology in text and figures in Section 8.3.14	48	• Corrected REG0x03 default charge current to 1A and max charge current to 3 A in Section 8.5.1	53	• Changed REG0x09 bit5 from RESERVED to STOP_WD_CHG in Section 8.5.1	53	• Added REG0x10 bits5-4 in Section 8.5.1	53	• Clarified REG0x14 and REG0x33 regarding reporting IBAT discharge current in Section 8.5.1	53	• Changed REG0x2E to no longer recommend 12-bit ADC setting in Section 8.5.1	53	• Changed REG0x2E to Running average (not available for IBAT discharge) in Section 8.5.1	53	• Corrected PN and DEV_REV naming in REG0x48 in Section 8.5.1	53	• Added optional input snubber/TVS to application diagrams in Section 9.2	126
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<p>These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/BQ25672 </p>																																													
Reason for Change:																																													
To accurately reflect device characteristics.																																													

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
Electrical specification performance changes as indicated above.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
BQ25672RQMR			

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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